## ABSTRACT OF THE INVENTION

The invention relates to a semiconductor structure that is formed by delaminating a semiconductor substrate and by bonding the top section of the substrate to a transfer substrate. Delaminating is carried out by causing a polymer film to achieve greater adhesion that an embrittlement layer in the semiconductor substrate.

"Express Mail" mailing label number: <u>EL873859619US</u>
Date of Deposit: <u>December 11, 2001</u>
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